ASSOCIATION CONNEC	© Copyright 2005. IP	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard http://www.ipc.org/IPC-175x Form Tyl Distribute													
Supplier Info	rmation														
Company name* Compa				ompany unique ID			Unique ID Authority					Response Date*			
nsemi												2025-08-02			
Contact Name			Title - Contac	et		P	Phone - Contact*				Email	Email - Contact*			
Product-Env-Ste	ewards		Product Envi	Product Enviro Compliance			NA				Produ	Product-Env-Stewards@onsemi.com			
Authorized Representative* Title - R				Fitle - Representative			Phone - Representative*				Email	Email - Representative*			
Product-Env-Ste	ewards	Product Enviro Compliance			N	NA				Produ	Product-Env-Stewards@onsemi.com				
Reque	ester Item Number	ter Item Number Mfr Iter		em Number Mfr Item Name]	Effective Date	Version	M	Manufacturing Site		Weig	Veight* UOM		Unit Type
		NCP186BMX185TAG Fast Transient res LDO. Act Discha			esponse Low Voltage arge, Vout= 1.85V	e 1A	2025-08-02 THB				2.5 mg		mg	Each	
Ianufacturi r	ng Proccess Informati	ion													
Termi	rminal Plating / Grid Array Material		Terminal Base Alloy J-		J-STD-020 MSL R	ating	Peak Process Body Temperature		Max Time a	t Peak Temper	ak Temperature		Number of Reflow Cycles		
Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)			CU Alloy 1		1		260		C 30		seco	seconds 3			
Comments		·		•			•	•		•	•				
vel 1 - maximu	m time at peak temperatui	e during so	ldering is 10-3	0 seconds											
or more inform	ation regarding material c	omposition	please refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its paragraph. If the Company and the Supplier supplier has provided certifications of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.13	mg	Supplier	Silicon (Si)	7440-21-3		0.13	mg
Die Attach	0.05	mg	Supplier	Silver (Ag)	7440-22-4		0.0375	mg
			Supplier	Epoxy resins	129915-35-1		0.0125	mg
Lead Frame	1.09		Supplier	Silver (Ag)	7440-22-4		0.0109	mg
			Supplier	Tin (Sn)	7440-31-5		0.0027	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0024	mg
			Supplier	Chromium (Cr)	7440-47-3		0.0027	mg
			Supplier	Copper (Cu)	7440-50-8		1.0713	mg
Mold Compound-Black	1.14	mg	Supplier	Epoxy and Phenolic Resin	40216-08-8		0.0912	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0057	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		0.0228	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		0.9861	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.0342	mg
Plating	0.02		Supplier	Palladium (Pd)	7440-05-3		0.0004	mg
			В	Nickel (Ni)	7440-02-0		0.0187	mg
			Supplier	Gold (Au)	7440-57-5		0.0008	mg
Wire Bond - Au	0.07	mg	Supplier	Gold (Au)	7440-57-5		0.07	mg